BGA416

RF Cascode Amplifier

Small Signal Discretes



Edition 2008-04-21

Published by Infineon Technologies AG, 81726 München, Germany © Infineon Technologies AG 2008. All Rights Reserved.

Attention please!

The information herein is given to describe certain components and shall not be considered as a guarantee of characteristics.

Terms of delivery and rights to technical change reserved.

We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.



BGA416, RF Cascode Amplifier

Revision History: 2008-04-21, Rev. 2.1

Previous Version: 2005-07-26

Page	Subjects (major changes since last revision)				
All	Document layout change				
4-5	Electrical Characteristics slightly changed				
7-8	Figures updated				

Trademarks

SIEGET® is a registered trademark of Infineon Technologies AG.



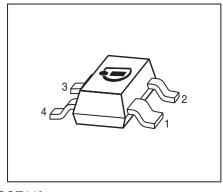
RF Cascode Amplifier

1 RF Cascode Amplifier

Feature

- G_{MA} = 23 dB at 900 MHz
- Ultra high reverse isolation, 60 dB at 900 MHz
- Low noise figure, $F_{50\Omega}$ = 1.2 dB at 900 MHz
- On chip bias circuitry, 5.5 mA bias current at $V_{\rm CC}$ = 3 V
- Typical supply voltage: 2.5 to 5.0 V
- SIEGET®-25 technology
- · Pb-free (RoHS compliant) package





SOT143

Applications

- Buffer amplifier
- LNAs
- · Oscillator active devices

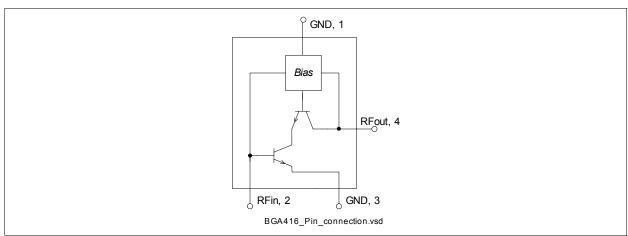


Figure 1 Pin connection

Description

BGA416 is a monolithic silicon cascode amplifier with high reverse isolation. A bias network is integrated for simplified biasing.

Туре	Package	Marking
BGA416	SOT143	C1s

Note: **ESD:** Electrostatic discharge sensitive device, observe handling precaution



Electrical Characteristics

Maximum Ratings

Table 1 Maximum ratings

Parameter	Symbol	Limit Value	Unit	
Voltage at pin RFout	V_{OUT}	6	V	
Device current ¹⁾	I_{D}	20	mA	
Current into pin RFin	I_{in}	0.5	mA	
Input power	P_{in}	8	dBm	
Total power dissipation, $T_{\rm S}$ < 123°C ²⁾	P_{tot}	100	mW	
Junction temperature	T_{J}	150	°C	
Ambient temperature range	T_{A}	-65 150	°C	
Storage temperature range	T_{STG}	-65 150	°C	

¹⁾ Device current is equal to current into pin RFout

Note: All Voltages refer to GND-Node

Thermal resistance

Table 2 Thermal resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}	270	K/W

¹⁾ For calculation of R_{thJA} please refer to Application Note Thermal Resistance

2 Electrical Characteristics

Electrical characteristics at $T_{\rm A}$ = 25 °C (measured in test circuit specified in Figure 2) $V_{\rm CC}$ = 3 V, unless otherwise specified

Table 3 Electrical Characteristics

Parameter	Symbol	Values		Unit	Note /	
		Min.	Тур.	Max.		Test Condition
Maximum available power gain	G_{MA}		23		dB	f = 0.9 GHz
			14		dB	f = 1.8 GHz
Insertion power gain	$ S_{21} ^2$		17		dB	f = 0.9 GHz
			11		dB	f = 1.8 GHz
Reverse isolation	$ S_{12} $		60		dB	f = 0.9 GHz
			40		dB	f = 1.8 GHz
Noise figure ($Z_{\rm S}$ = 50 Ω)	$F_{50\Omega}$		1.2		dB	f = 0.9 GHz
			1.6		dB	f = 1.8 GHz
Output power at 1 dB gain	$P_{ ext{-1dB}}$		-3		dBm	f = 0.9 GHz
compression ($Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω)			-3		dBm	f = 1.8 GHz
Output third order intercept point	OIP ₃		14		dBm	f = 0.9 GHz
$(Z_{\rm S} = Z_{\rm L} = 50 \ \Omega)$			14		dBm	f = 1.8 GHz
Device current	I_{D}		5.5		mA	

²⁾ $T_{\rm S}$ is measured on the ground lead at the soldering point



Electrical Characteristics

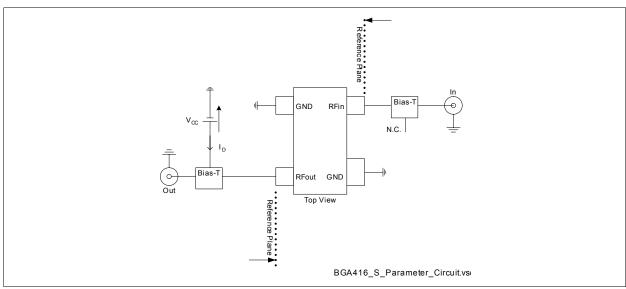


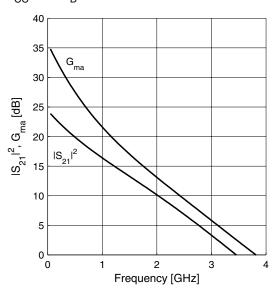
Figure 2 Test Circuit for Electrical Characteristics



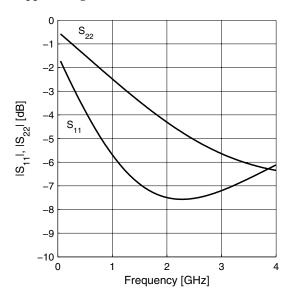
Measured Parameters

3 Measured Parameters

Power Gain
$$|S_{21}|^2$$
, $G_{ma} = f(f)$
 $V_{CC} = 3V$, $I_D = 5.5mA$

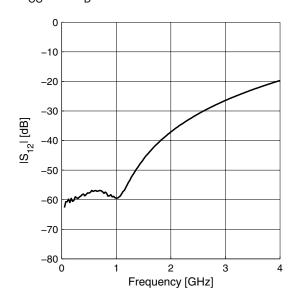


$$\begin{aligned} & \textbf{Matching} \ |S_{11}|, \ |S_{22}| = f(f) \\ & V_{CC} = 3V, \ I_D = 5.5 \text{mA} \end{aligned}$$



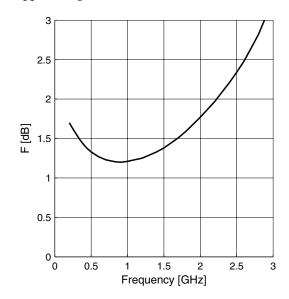
Reverse Isolation $|S_{12}| = f(f)$

$$V_{CC} = 3V, I_{D} = 5.5 \text{mA}^{'}$$



Noise figure F = f(f)

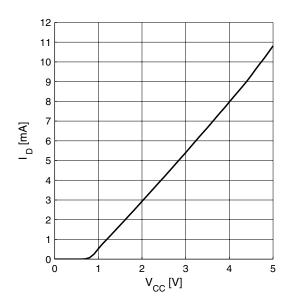
$$V_{CC} = 3V, I_{D} = 5.5 \text{mA}$$



Package Information



Device Current $I_D = f(V_{CC})$



4 Package Information

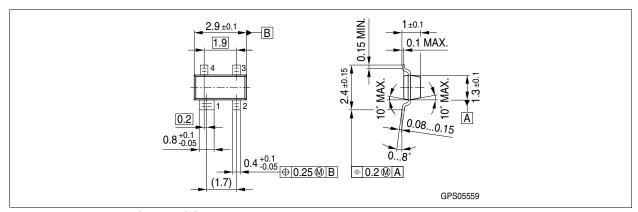


Figure 3 Package Outline SOT143

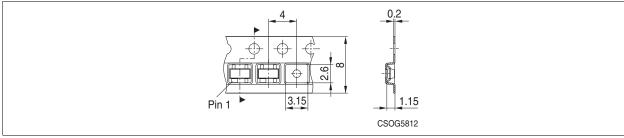


Figure 4 Tape for SOT143